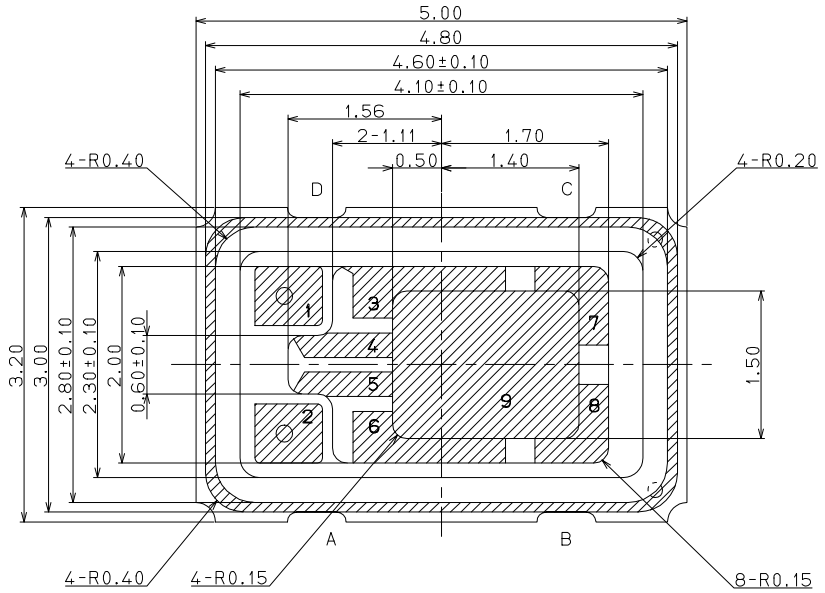

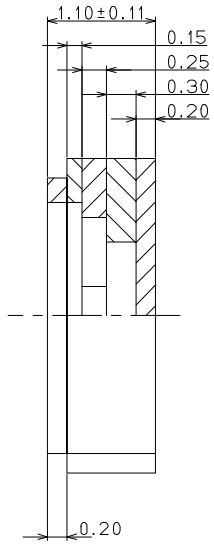

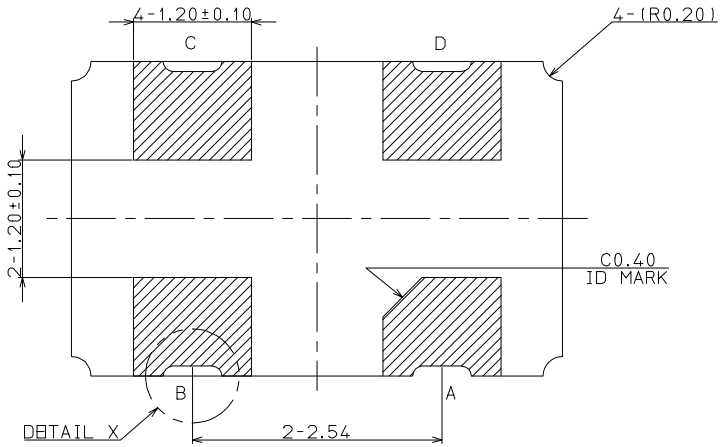

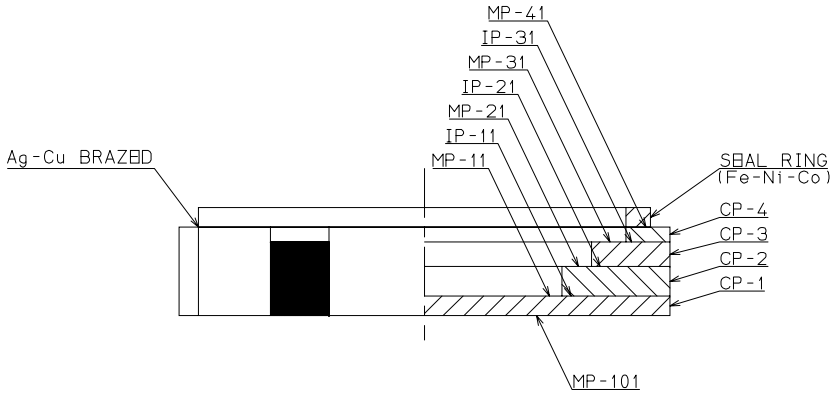

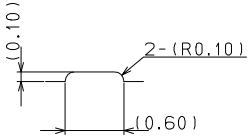

DETAIL X
(4 PLCS.)

NOTES:

1. PLATING
   ELECTRO Ni : 2.00~6.00 MICRON.
   ELECTRO Au : 0.70~1.20 MICRON.
2. CAMBER : ±50.00 MICRON MAX.
3. CONNECTION :
   (1-4),(2-5),(3-A),(7-9-D),(6-B-S/R),(8-C).
4. GENERAL TOLERANCE : ±1% N.L.T. ±0.13
5. STRESS RELAXATION DESIGN SHALL BE APPLIED ON THIS ITEM.
6. EXPOSURE OF CERAMIC SURFACE AND METALLIZED PATTERN OCCURRED BY MISALIGNMENT OF THE UPPER LAYER, SHALL BE ALLOWED.
7. ■ PART TO BE SHOWN AS SIDE METALLIZED PATTERN.
8. SEALING METHOD OF THIS PRODUCT SHALL BE SEAM WELD.
9. AIR BLOW SPECIFICATIONS.

TOLERANCE: ±1% N.L.T.±0.13, ANGLES	REVISION: SEE ATTACHED EXCEPTIONS SHEET.				TITLE: 5.0 x 3.2mm CMOS Osc Pkg
	SCALE: 20 : 1	DIMENSION: mm	PROJECTION: 3rd	CUSTOMER DWG NO. / REV.	
MATERIAL: 90%MIN.Al2O3 (NA-311B BLACK)	APPROVED: Shigetomi	CHECKED: Koike	ENGRG: Ohba	CHECKED: Kumura	DESIGNED: Sugi
	May.09.03	May.09.03	May.09.03	May.09.03	May.09.03

PART NO. S5032CLK1 REV. 0
DWG NO. SHT/OF 1/9

VC America, Inc. sales@vcamerica.com

Sumitomo Metal (SMI) Electronics Devices Inc.